

NOTES:

1. MATERIAL:

HOLD DOWN: COPPER ALLOY.

HOUSING: HIGH TEMPERATURE THERMOPLASTIC, UL 94V-0 RATED.

TERMINAL: COPPER ALLOY.

2. TIN/LEAD PLATING SPEC:

HOLD DOWN : TIN/LEAD PLATED WITH 100u" MIN.,
OVER 50u" MIN. NICKEL UNDERPLATED.

TERMINAL : 50u"MIN. NICKEL UNDERPLATED OVER ALL
100u" MIN. TIN/LEAD PLATED IN SOLDERING AREA,
SELECTIVE GOLD PLATED IN CONTACT AREA.

3. LEAD-FREE PLATING SPEC:

HOLD DOWN : PURE MATTE TIN PLATED WITH 100u" MIN.,
OVER 50u" MIN. NICKEL UNDERPLATED.

TERMINAL : 50u" MIN. NICKEL UNDERPLATED OVER ALL
100u" MIN. PURE MATTE TIN PLATED IN SOLDERING AREA,
SELECTIVE GOLD PLATED IN CONTACT AREA.

4. THE HOUSING WILL WITHSTAND EXPOSURE TO 260 DEGREE C PEAK TEMPERATURE FOR 10 SECONDS IN A CONVECTION, INFRA-RED OR VAPOR PHASE REFLOW OVEN.

5.PRODUCT SPEC NO: GS-12-240.

PACKAGE SPEC NO: GS-14-961.

6. THIS PRODUCT (10054310-XXXXXL) MEETS THE EUROPEAN UNION DIRECTIVE AS DESCRIBED IN GS-22-008, SUB CLAUSE 3.1 (DIRECTIVE 2002/95/EC).

7. PART NUMBER DESCRIPTION:

10054310-X X 50 X X

LEAD-FREE PLATING OPTION:

BLANK: TIN/LEAD PLATING SPEC (SEE NOTE 2).

LF: LEAD-FREE PLATING SPEC (SEE NOTE 3).

PACKAGING METHOD:
BLANK: PVC TRAY.

KEY TYPE, SEE TABLE-2.

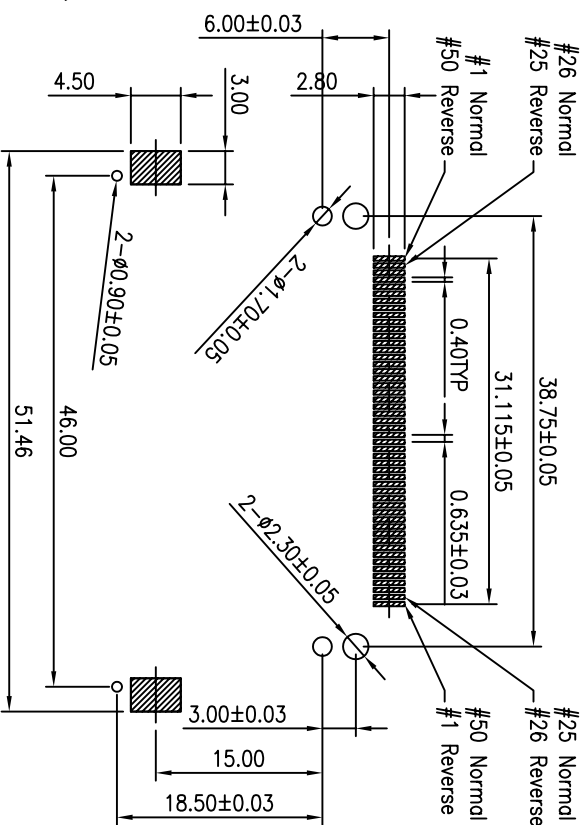
0: NORMAL TYPE

1: REVERSE TYPE

CONTACT AREA PLATING:

D: 15u" GOLD.

E: 30u" GOLD.



RECOMMENDED P.C.B. LAYOUT
GENERAL TOLERANCE: $\pm 0.05\text{mm}$.

mat'l. code				tolerances unless otherwise specified		CUSTOMER COPY		A FCI www.fciconnect.com	
ltr	ecn	no	dr	date	.X ±.38 .XX ±.25 .XXX ±.10	projection 	title CF CARD HEADER SLIM TYPE	product family CF	code —
A				linear					
				angles					
				0° ±2°					
					dr	ALLEN CHANG	3/21/05	MM	
					engr	ALLEN CHANG	3/21/05	←	
					chr	STERLING LIN	3/21/05	→	
					oppd	H.C. LIU	3/21/05	scale	
								N/A	A4
sheet		revision	A	A					
index		sheet	1	2					